

Sung Yi

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66

papers

1,178

citations

21

h-index

32

g-index

76

ext. papers

1,343

ext. citations

2.5

avg, IF

4.06

L-index

#	Paper	IF	Citations
66	Thermal transient characteristics of die attach in high power LED PKG. <i>Microelectronics Reliability</i> , 2008 , 48, 445-454	1.2	111
65	The significance of (an)isotropic viscoelastic Poisson ratio stress and time dependencies. <i>International Journal of Solids and Structures</i> , 1998 , 35, 3081-3095	3.1	77
64	Fracture toughening mechanism of shape memory alloys due to martensite transformation. <i>International Journal of Solids and Structures</i> , 2000 , 37, 5315-5327	3.1	69
63	Fracture toughening mechanism of shape memory alloys under mixed-mode loading due to martensite transformation. <i>International Journal of Solids and Structures</i> , 2001 , 38, 4463-4476	3.1	56
62	A finite element approach for cure simulation of thermosetting matrix composites. <i>Computers and Structures</i> , 1997 , 64, 383-388	4.5	54
61	Dynamic finite element analysis of viscoelastic composite plates in the time domain. <i>International Journal for Numerical Methods in Engineering</i> , 1994 , 37, 4081-4096	2.4	53
60	Large deformation finite element analyses of composite structures integrated with piezoelectric sensors and actuators. <i>Finite Elements in Analysis and Design</i> , 2000 , 35, 1-15	2.2	52
59	A hybrid stress ANS solid-shell element and its generalization for smart structure modelling. Part II Smart structure modelling. <i>International Journal for Numerical Methods in Engineering</i> , 2000 , 48, 565-582	2.4	50
58	Solder joint reliability of plastic ball grid array packages. <i>Soldering and Surface Mount Technology</i> , 1999 , 11, 44-48	1.4	47
57	Anisotropic viscoelastic finite element analysis of mechanically and hygrothermally loaded composites. <i>Composites Part B: Engineering</i> , 1993 , 3, 123-135		39
56	An effective inclusion model for effective moduli of heterogeneous materials with ellipsoidal inhomogeneities. <i>International Journal of Solids and Structures</i> , 2001 , 38, 5789-5805	3.1	38
55	Finite element formulation for anisotropic coupled piezoelectro-hygro-thermo-viscoelasto-dynamic problems. <i>International Journal for Numerical Methods in Engineering</i> , 1999 , 45, 1531-1546	2.4	29
54	Effects of Thermo-Mechanical Properties of Composites on Viscosity, Temperature and Degree of Cure in Thick Thermosetting Composite Laminates during Curing Process. <i>Journal of Composite Materials</i> , 1998 , 32, 600-622	2.7	27
53	Hygrothermal effects on viscoelastic responses of laminated composites. <i>Composites Part B: Engineering</i> , 1995 , 5, 183-193		27
52	Stochastic Viscoelastic Delamination Onset Failure Analysis of Composites. <i>Journal of Composite Materials</i> , 1993 , 27, 1097-1113	2.7	26
51	Analytical formulation of optimum material properties for viscoelastic damping. <i>Smart Materials and Structures</i> , 1992 , 1, 113-122	3.4	25
50	Nonlinear Thermo-Viscoelastic Analysis of Interlaminar Stresses in Laminated Composites. <i>Journal of Applied Mechanics, Transactions ASME</i> , 1996 , 63, 218-224	2.7	24

49	A Viscoplastic Constitutive Model for 63Sn37Pb Eutectic Solders. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2002 , 124, 91-96	2	23
48	New solutions for effective elastic moduli of microcracked solids. <i>International Journal of Solids and Structures</i> , 2000 , 37, 3525-3534	3.1	22
47	Residual stresses in plastic IC packages during surface mounting process preceded by moisture soaking test. <i>IEEE Transactions on Advanced Packaging</i> , 1997 , 20, 247-255		21
46	Thermoviscoelastic analysis of delamination onset and free edge response in laminated composites. <i>AIAA Journal</i> , 1993 , 31, 2320-2328	2.1	21
45	Dynamic Responses of Plates With Viscoelastic Free Layer Damping Treatment. <i>Journal of Vibration and Acoustics, Transactions of the ASME</i> , 1996 , 118, 362-367	1.6	19
44	Effects of oxidation and plasma cleaning on the adhesion strength of molding compounds to copper leadframes. <i>Journal of Adhesion Science and Technology</i> , 1999 , 13, 789-804	2	18
43	Mechanical properties of cellular materials. I. Linear analysis of hexagonal honeycombs. <i>Journal of Applied Polymer Science</i> , 1997 , 63, 383-393	2.9	15
42	A failure criterion for debonding between encapsulants and leadframes in plastic IC packages. <i>Journal of Adhesion Science and Technology</i> , 2000 , 14, 93-105	2	15
41	A novel integrated silicon capacitive microphone-floating electrode "electret" microphone (FEEM). <i>Journal of Microelectromechanical Systems</i> , 1998 , 7, 224-234	2.5	14
40	Finite element analysis for microwave cure of underfill in flip chip packaging. <i>Thin Solid Films</i> , 2004 , 462-463, 436-445	2.2	14
39	Bonding strengths at plastic encapsulant-gold-plated copper leadframe interface. <i>Microelectronics Reliability</i> , 2000 , 40, 1207-1214	1.2	14
38	Finite element analysis of moisture distribution and hygrothermal stresses in TSOP IC packages. <i>Finite Elements in Analysis and Design</i> , 1998 , 30, 65-79	2.2	13
37	Nonlinear Viscoelastic Finite Element Analyses of Thermosetting Polymeric Composites during Cool-Down after Curing. <i>Journal of Composite Materials</i> , 2002 , 36, 3-17	2.7	13
36	A finite element formulation for composite laminates with smart constrained layer damping. <i>Advances in Engineering Software</i> , 2000 , 31, 529-537	3.6	13
35	A study on corrugated diaphragms for high-sensitivity structures. <i>Journal of Micromechanics and Microengineering</i> , 1997 , 7, 310-315	2	12
34	CURE-CYCLE SIMULATIONS OF COMPOSITES WITH TEMPERATURE- AND CURE-DEPENDENT ANISOTROPIC VISCOELASTIC PROPERTIES AND STOCHASTIC DELAMINATIONS. <i>Mechanics of Advanced Materials and Structures</i> , 1998 , 5, 81-101	1.8	12
33	Finite element analysis of composite structures with smart constrained layer damping. <i>Advances in Engineering Software</i> , 1998 , 29, 265-271	3.6	9
32	Probabilistic analysis of delamination onset in linear anisotropic elastic and viscoelastic composite columns. <i>Reliability Engineering and System Safety</i> , 1997 , 56, 237-248	6.3	8

31	Real-Time Quality Evaluation of Wire Bonding Using Input Impedance. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2006 , 29, 280-284		8
30	Nonlinear viscoelastic stress singularities near free edges of unsymmetrically laminated composites. <i>International Journal of Solids and Structures</i> , 1998 , 35, 3221-3237	3.1	7
29	FINITE ELEMENT ALGORITHMS FOR DYNAMIC SIMULATIONS OF VISCOELASTIC COMPOSITE SHELL STRUCTURES USING CONJUGATED GRADIENT METHOD ON COARSE GRAINED AND MASSIVELY PARALLEL MACHINES. <i>International Journal for Numerical Methods in Engineering</i> , 1997 , 40, 1857-1875	2.4	6
28	Chemothermal modeling and finite-element analysis for microwave cure process of underfill in flip-chip packaging. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2005 , 28, 355-363		6
27	Machine learning framework for predicting reliability of solder joints. <i>Soldering and Surface Mount Technology</i> , 2019 , 32, 82-92	1.4	6
26	Free Edge Stresses in Elastic and Viscoelastic Composites Under Uniaxial Extension, Bending, and Twisting Loadings. <i>Journal of Engineering Materials and Technology, Transactions of the ASME</i> , 1997 , 119, 266-272	1.8	5
25	Effective transverse Young's modulus of composites with viscoelastic interphase. <i>AIAA Journal</i> , 1995 , 33, 1548-1550	2.1	5
24	The Optimization of Machining Parameters for Milling Operations by Using the Nelder-Mead Simplex Method. <i>Journal of Manufacturing and Materials Processing</i> , 2020 , 4, 66	2.2	5
23	Analysis of warpage and residual stress in plastic ball grid array package after post mold cure. <i>Microelectronics International</i> , 2012 , 29, 163-171	0.8	4
22	Effects of Packaging Materials on the Reliability of System in Package 2007 ,		4
21	. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2003 , 26, 205-210		4
20	Stochastic Delamination Simulations of Nonlinear Viscoelastic Composites During Cure. <i>Journal of Sandwich Structures and Materials</i> , 1999 , 1, 111-127	2.1	4
19	Effects of a time-dependent interfacial layer on the thermo-mechanical response of polymer matrix composites. <i>Journal of Materials Processing Technology</i> , 1997 , 67, 183-188	5.3	3
18	An optical characterization technique for hygroscopic expansion of polymers and plastic packages. <i>Microelectronics Reliability</i> , 2006 , 46, 600-609	1.2	3
17	Time-domain analyses of acoustics-structure interactions for piezoelectric transducers. <i>Journal of the Acoustical Society of America</i> , 2001 , 109, 2762-70	2.2	3
16	Approximate Evaluation for Effective Elastic Moduli of Cracked Solids. <i>International Journal of Fracture</i> , 2000 , 106, 15-20	2.3	3
15	A viscoplastic constitutive model for 63Sn37Pb eutectic solders		3
14	Estimation of Al/Cu laser weld penetration in photodiode signals using deep neural network classification. <i>Journal of Laser Applications</i> , 2021 , 33, 042009	2.1	3

13	Cure cycle simulations of composites with temperature and cure dependent anisotropic viscoelastic properties 1996 ,		2
12	Generalized Viscoelastic 1-DOF Deterministic Nonlinear Oscillators. <i>Nonlinear Dynamics</i> , 2004 , 36, 281-298		2
11	A sensitivity study of viscoelastic, structural and piezo-electric damping for flutter control 1998 ,		2
10	The Green Synthesis of 2D Copper Nanosheets and Their Light Absorption. <i>Materials</i> , 2021 , 14,	3.5	2
9	Fatigue Characteristic Analysis of New ECO7175v1 Extruded Aluminum Alloy. <i>Journal of Aerospace Engineering</i> , 2019 , 32, 04018128	1.4	2
8	Failure-Oriented-Accelerated-Testing and Its Role in Making a Device into a Product 2019 ,		1
7	Shear strengths of CBGA/PBGA solder ball joints with lead-free solder pastes. <i>International Journal of Materials and Structural Integrity</i> , 2014 , 8, 62	0.3	1
6	Study of low-modulus die attach adhesives and molding compounds on warpage and damage of PBGA		1
5	Hygro-thermo-mechanical behavior of molding compounds at elevated environments		1
4	Thermoviscoelastic analysis of delamination onset and free edge response in epoxy matrix composite laminates 1991 ,		1
3	Comprehensive Analysis of the Microstructure and Mechanical Properties of Friction-Stir-Welded Low-Carbon High-Strength Steels with Tensile Strengths Ranging from 590 MPa to 1.5 GPa. <i>Applied Sciences (Switzerland)</i> , 2021 , 11, 5728	2.6	0
2	High-Entropy Alloys Properties Prediction Model by Using Artificial Neural Network Algorithm. <i>Metals</i> , 2021 , 11, 1559	2.3	0
1	Microstructure and Mechanical Properties of Cast and Hot-Rolled Medium-Carbon Steels under Isothermal Heat-Treatment Conditions. <i>Metals</i> , 2021 , 11, 1950	2.3	